



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

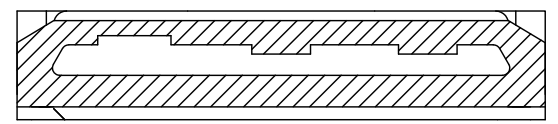
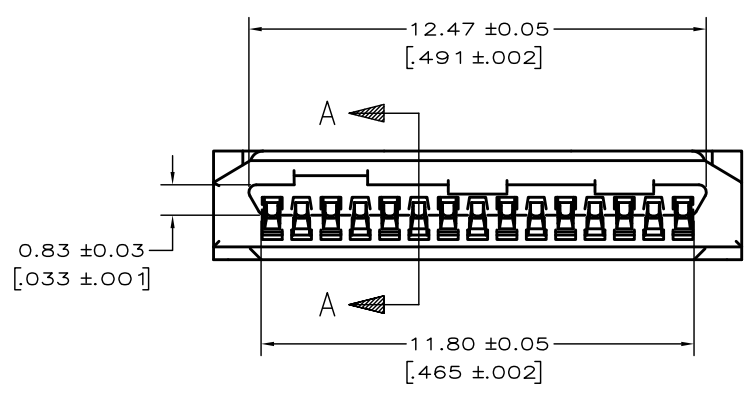
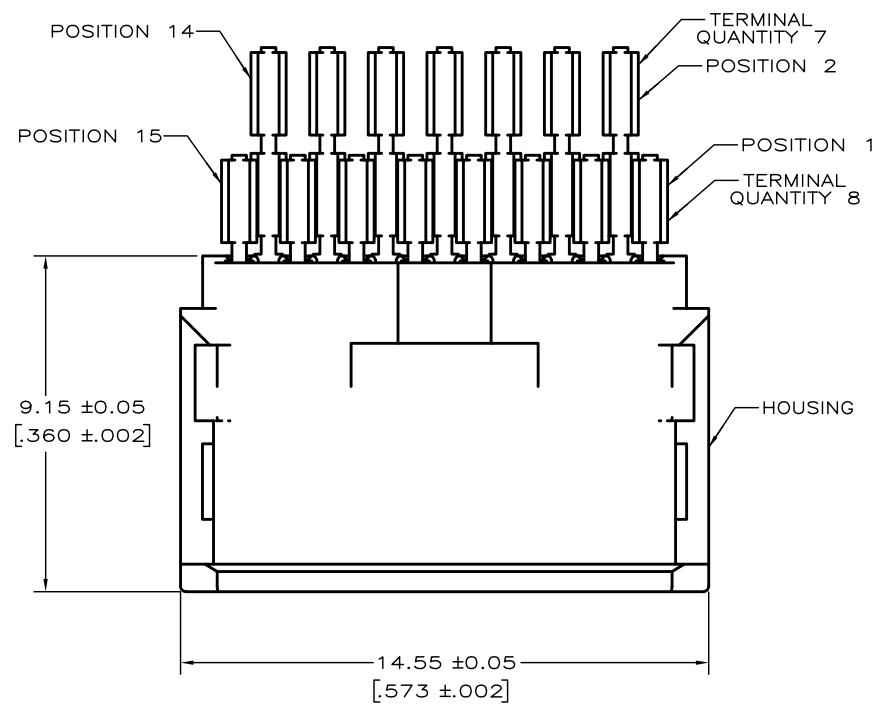
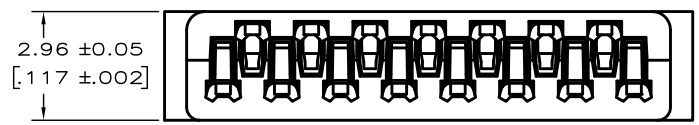
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

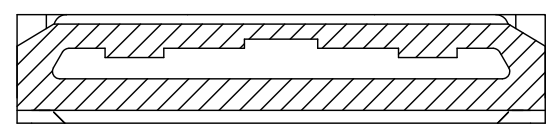


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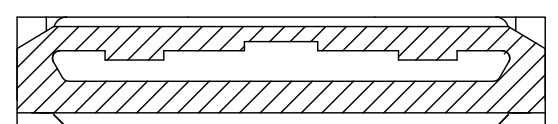
REVISONS		DATE	BY	APP'D
A1	REVISED (ECR-14-006391)	21AUG14	BW	SC



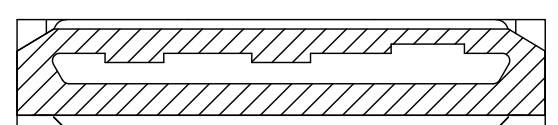
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TBD



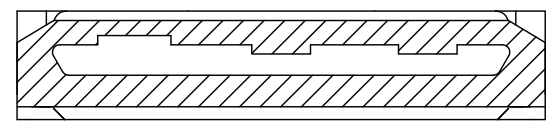
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KEY 4
LAN



5558666-3
KEY 3
MODEM

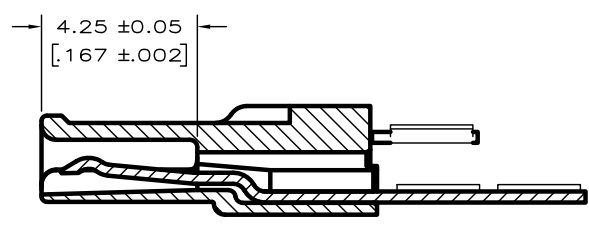


5558666-2
KEY 2
MULTI-FUNCTION



5558666-1
KEY 1
CLOSED

KEYING OPTIONS
SOME DETAIL OMITTED FOR CLARITY



SECTION A-A

- △ HOUSING: NYLON MOLDING COMPOUND, BLACK.
 - TERMINALS: 0.3[.012] THICK PHOS BRONZE.
 - PLATING: NICKEL UNDERPLATE OVER ENTIRE TERMINAL. 2.54μm[.000100] MINIMUM THICKNESS.
 - LOCALIZED PLATING AREA: 0.254μm[.000010] THICK GOLD OVER 1.016μm[.000040] MINIMUM THICK PALLADIUM NICKEL (OVER 0.051μm[000002] MINIMUM THICK GOLD WHEN REQUIRED BY PROCESS CONDITIONS).
 - SOLDERABLE AREA PLATED WITH MATTE TIN 3.81 MICRONS MINIMUM THICK.
2. 5558666-1 KEY1 (CLOSED) AS SHOWN.

DESCRIPTION	PART NUMBER
KEY 5	5558666-5
OBSOLETE KEY 4	5558666-4
OBSOLETE KEY 3	5558666-3
KEY 2	5558666-2
OBSOLETE KEY 1	5558666-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DRW: B. LATTUCA 10AUG08
 CHK: D. GORENC 10AUG08
 APP'D: M. WALMSLEY 10AUG08

TE Connectivity

CONNECTOR ASSEMBLY, CABLE, 15 POSITION, INFOPORT, SERIES III

SCALE: 10:1 SHEET 1 OF 1 REV A1